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[ON Semiconductor](#)  
[MMVL3700T1](#)

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# MMVL3700T1

## High Voltage Silicon Pin Diode

These devices are designed primarily for VHF band switching applications but are also suitable for use in general-purpose switching circuits. They are supplied in a cost-effective plastic surface mount package for economical, high-volume consumer and industrial requirements.

### Features

- Long Reverse Recovery Time:  $t_{rr} = 300$  ns (Typ)
- Rugged PIN Structure Coupled with Wirebond Construction for Optimum Reliability
- Low Series Resistance @ 100 MHz:  
 $R_S = 0.7 \Omega$  (Typ) @  $I_F = 10$  mAdc
- Reverse Breakdown Voltage = 200 V (Min)
- Pb-Free Package is Available

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	$V_R$	200	Vdc
Peak Forward Current	$I_F$	20	mAdc

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, $T_A = 25^\circ\text{C}$ (Note 1) Derate above $25^\circ\text{C}$	$P_D$	200 1.57	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	635	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	$T_J, T_{stg}$	150	$^\circ\text{C}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

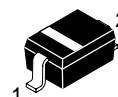
1. FR-4 Minimum Pad



ON Semiconductor®

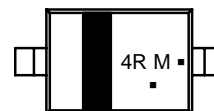
<http://onsemi.com>

### SILICON PIN SWITCHING DIODE



PLASTIC  
SOD-323  
CASE 477  
STYLE 1

### MARKING DIAGRAM



4R = Device Code  
 M = Date Code\*  
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

### ORDERING INFORMATION

Device	Package	Shipping†
MMVL3700T1	SOD-323	3000/Tape & Reel
MMVL3700T1G	SOD-323 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## MMVL3700T1

### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ( $I_R = 10 \mu\text{A}$ )	$V_{(BR)R}$	200	-	-	Vdc
Diode Capacitance ( $V_R = 20 \text{ Vdc}$ , $f = 1.0 \text{ MHz}$ )	$C_T$	-	-	1.0	pF
Series Resistance ( $I_F = 10 \text{ mA}$ )	$R_S$	-	0.7	1.0	$\Omega$
Reverse Leakage Current ( $V_R = 150 \text{ Vdc}$ )	$I_R$	-	-	0.1	$\mu\text{A}$
Reverse Recovery Time ( $I_F = I_R = 10 \text{ mA}$ )	$t_{rr}$	-	300	-	ns

### TYPICAL CHARACTERISTICS

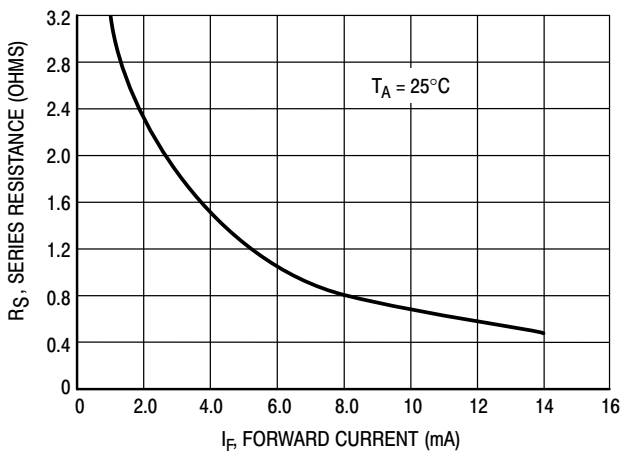


Figure 1. Series Resistance

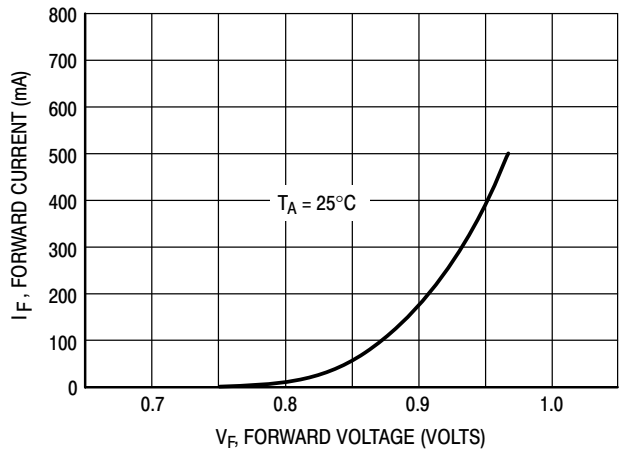


Figure 2. Forward Voltage

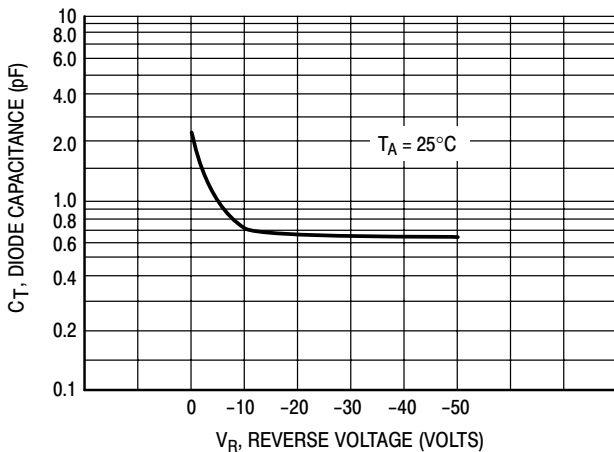


Figure 3. Diode Capacitance

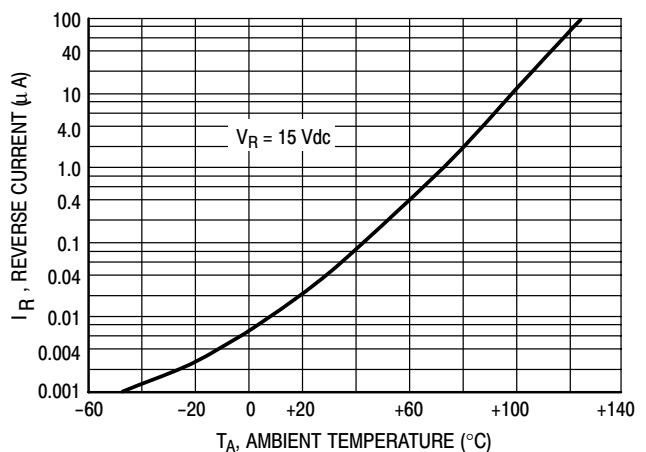
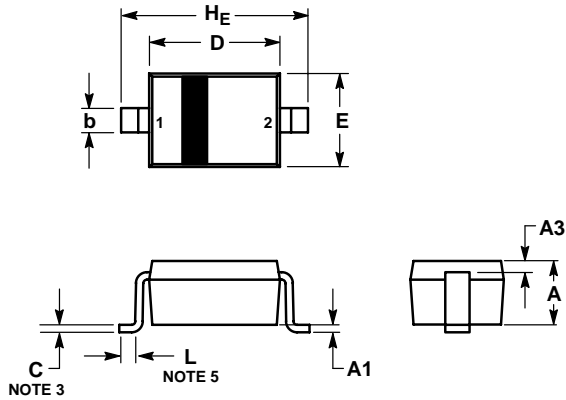


Figure 4. Leakage Current

## MMVL3700T1

### PACKAGE DIMENSIONS

SOD-323  
 CASE 477-02  
 ISSUE G



NOTES:

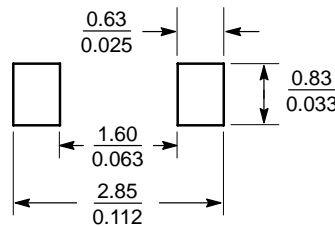
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURED FROM END OF RADIUS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

STYLE 1:

1. CATHODE
2. ANODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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